

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YONG ZHANG	08/17/2020
CHENGKAI WU	08/17/2020
HAN WANG	08/17/2020
HAOMIAO WEI	08/17/2020
RUIMIN XU	08/17/2020
BO YAN	08/17/2020
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	UNIVERSITY OF ELECTRONIC SCIENCE AND TECHNOLOGY OF CHINA
<b>Street Address:</b>	NO. 2006, XIYUAN AVENUE, WESTERN HIGH-TECH DISTRICT, CHENGDU, CHINA
<b>City:</b>	CHENGDU
<b>State/Country:</b>	CHINA
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17078109
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Email:</b>	in@bayramoglu-legal.com
<b>Correspondent Name:</b>	GOKALP BAYRAMOGLU
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<b>ATTORNEY DOCKET NUMBER:</b>	GBCD066-PKG
<b>NAME OF SUBMITTER:</b>	GOKALP BAYRAMOGLU
<b>SIGNATURE:</b>	/GOKALP BAYRAMOGLU/
<b>DATE SIGNED:</b>	10/23/2020
<b>Total Attachments: 2</b>	
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source=GBCD066-PKG-assignment#page2.tif	

ASSIGNMENT

- |  |                |                 |
|--|----------------|-----------------|
| <i>(1-8) Insert Name(s) of Inventor(s)</i> | (1) Yong ZHANG | (2) Chengkai WU |
|  | (3) Han WANG   | (4) Haomiao WEI |
|  | (5) Ruimin XU  | (6) Bo YAN      |
- 

For good and valuable consideration receipt of which is hereby acknowledged, the undersigned agree(s) to assign, and hereby do(es) assign, transfer and set over to:

<i>(9) Insert name of Assignee</i>	(9) University of Electronic Science and Technology of China
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<i>(10) Insert state of incorporation of Assignee</i>	(10) China
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<i>(11) Insert address of Assignee</i>	(11) of No. 2006, Xiyuan Avenue, Western High-Tech District, Chengdu, China (hereinafter designated as the Assignee) the entire worldwide right, title, interest, and patent applications and patents for every country, including divisions, reissues, continuations and all other extensions, rights and priorities in the invention known as and subject matter contained in
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<i>(12) Insert Identification of Invention, such as Title, Case Number or Foreign Application Number</i>	(12) <u>Double Schottky-Barrier Diode</u>
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<i>(13) Insert Date of Filing of Application</i>	(13) <u>Application is attached hereto.</u>
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1) The undersigned agree(s) to execute all papers necessary in connection with the application and any continuing or division applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

2) The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

3) The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

4) The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

5) The undersigned hereby authorize(s) and request(s) the Commissioner for Patents and the duly constituted authorities of foreign countries to issue any and all Letters Patents resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, its successors and assigns, as Assignee of the entire right, title and interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed and will not execute, any agreement in conflict herewith.

6) *The undersigned hereby grant(s)*

*Gokulp Bayramoglu, Reg.No. 66395*

*the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.*

Date Aug. 17, 2020 Yong Zhang  
Yong ZHANG

Date Aug. 17, 2020 Chengkai Wu  
Chengkai WU

Date Aug. 17, 2020 Han Wang  
Han WANG

Date Aug. 17, 2020 Haomiao Wei  
Haomiao WEI

Date Aug. 17, 2020 Ruilin Xu  
Ruilin XU

Date Aug. 17, 2020 Bo Yan  
Bo YAN